

IN THE CLAIMS

Please cancel claims 66-75 without prejudice.

Please enter the following claims:

54. (Once Amended) A polish pad comprising:

- a pad center area, said pad center area corresponding to a wafer center area;
a first set of grooves disposed in said pad center area, said first set of grooves having a first depth;
a pad edge area disposed adjacent to said pad center area, said pad edge area corresponding to a wafer edge area; and
a second set of grooves disposed in said pad edge area, said second set of grooves having a second depth.

55. (Unchanged) The polish pad of claim 54 wherein said first depth is smaller than said second depth.

56. (Unchanged) The polish pad of claim 54 wherein said first depth is within the range of approximately 1-90 % of said pad thickness.

57. (Unchanged) The polish pad of claim 54 wherein said second depth is within the range of approximately 1-90 % of said pad thickness.

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58. (Unchanged) The polish pad of claim 54 wherein said first set of grooves and said second set of grooves differ in shape.

59. (Once Amended) A polish pad comprising:

a pad center area, said pad center area corresponding to a wafer center area;
a first set of grooves disposed in said pad center area, said first set of grooves having a first width;

a pad edge area disposed adjacent to said pad center area, said pad edge area corresponding to a wafer edge area; and

a second set of grooves disposed in said pad edge area, said second set of grooves having a second width.

60. (Unchanged) The polish pad of claim 59 wherein said first width is smaller than said second width.

61. (Unchanged) The polish pad of claim 59 wherein said first width is within a range of approximately 1-100 mils.

62. (Unchanged) The polish pad of claim 59 wherein said second width is within the range of approximately 1-100 mils.

63. (Unchanged) The polish pad of claim 59 wherein said first set of grooves and said second set of grooves differ in shape.

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64. (Once Amended) A polish pad comprising:

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a pad center area, said pad center area corresponding to a wafer center area;
a first set of grooves disposed in said pad center area, said first set of grooves having a first density;

a pad edge area disposed adjacent to said pad center area, said pad edge area corresponding to a wafer edge area; and

a second set of grooves disposed in said pad edge area, said second set of grooves having a second density.

65. (Unchanged) The polish pad of claim 64 wherein said first density is smaller than said second density.

66. (Unchanged) The polish pad of claim 64 wherein said first density is within a range of approximately 2-50 grooves/inch.

67. (Unchanged) The polish pad of claim 64 wherein said second density is within a range of approximately 2-50 grooves/inch.